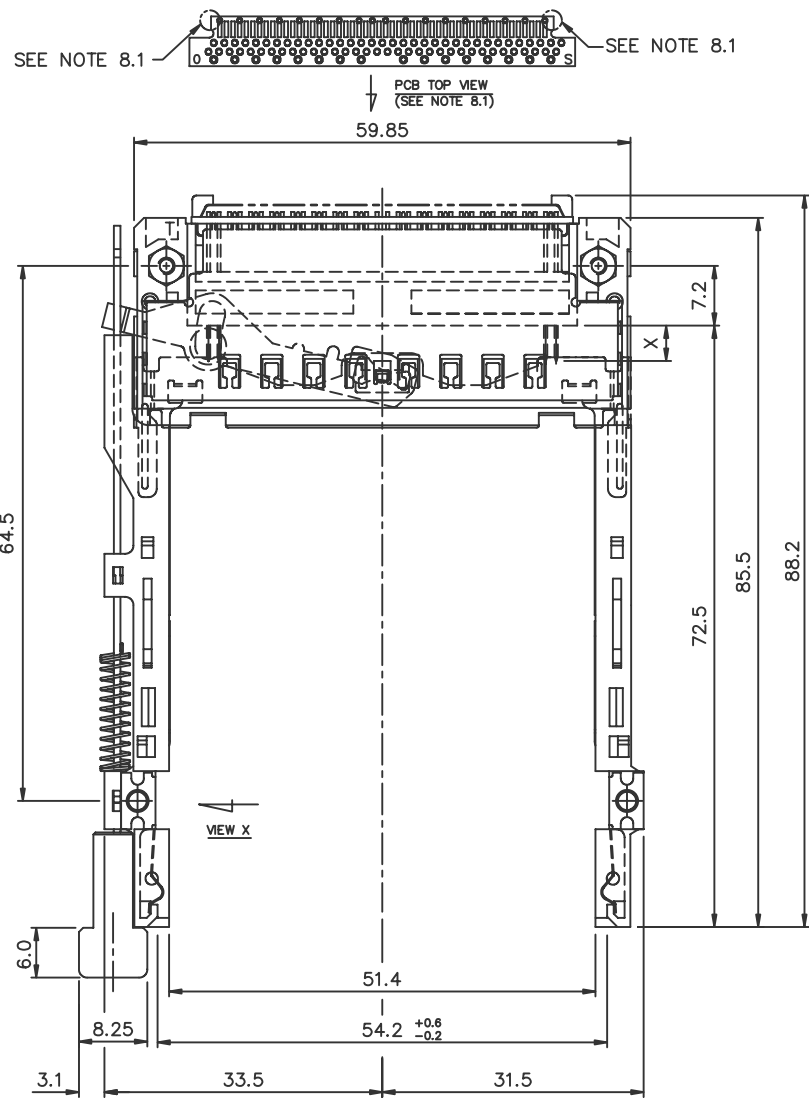


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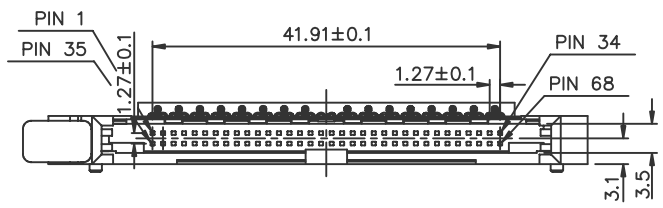
PRODUCT NO.  
52366-100DAS/100DASLF



- NOTES:
- 8.0mm MIN CARD EJECT.
  - EJECT TRAVEL: 9.50mm
  - MATERIAL:  
EJECT HEADER ASS'Y  
PLASTIC HOUSING: LCP UL94V-0 BLACK  
PIN: COPPER ALLOY  
PCB: FR4  
PLASTIC GUIDE: POLYPHTHARAMID UL94V-0 COLOR : BLACK.  
PLATE: STAINLESS  
EMI CONTACT: PHOSPHOR BRONZE
  - FINISH  
PIN:  
UNDER PLATING: 0.5um MIN. Ni  
CONTACT AREA: 0.1um MIN. GOLD OVER  
0.5um MIN. Pd-Ni  
SOLDER TAIL(TIN LEAD OPTION): 2.5um MIN. Sn-Pb  
SOLDER TAIL(LEAD FREE OPTION): 2.5um MIN. PURE TIN  
GROUND SHIELD :  
UNDER PLATING: 0.75um MIN. Ni  
CONTACT SURFACE: 0.2 um GOLD.
  - PUSH ROD LOCATION AND P.C.B. ARE AS APPEARS INSTALLED
  - DIM "X"
- |        |          |                  |         |
|--------|----------|------------------|---------|
|        | 4.25±0.1 | 3.5±0.1          | 5.0±0.1 |
| OTHERS | 36,67    | 1,17,34,35,51,68 |         |
- DO NOT TOUCH AND KEEP CLEAN THE SURFACES OF PCB OF HEADER ASS'Y.
  - SPECIAL FEATURES:  
8.1 NO CHAMFER OF VTB  
8.2 NO "S"-SLOT
  - IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
  - IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
  - LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION

ORDERING INFORMATION

NAME	PART NO.	Q'TY
(A) EJECT HEADER ASS'Y	52366-100DAS/100DASLF	1
(B) MATING RECEPTACLE	73277-101002/101002LF	1



VIEW X  
(SEE NOTE 8.2)

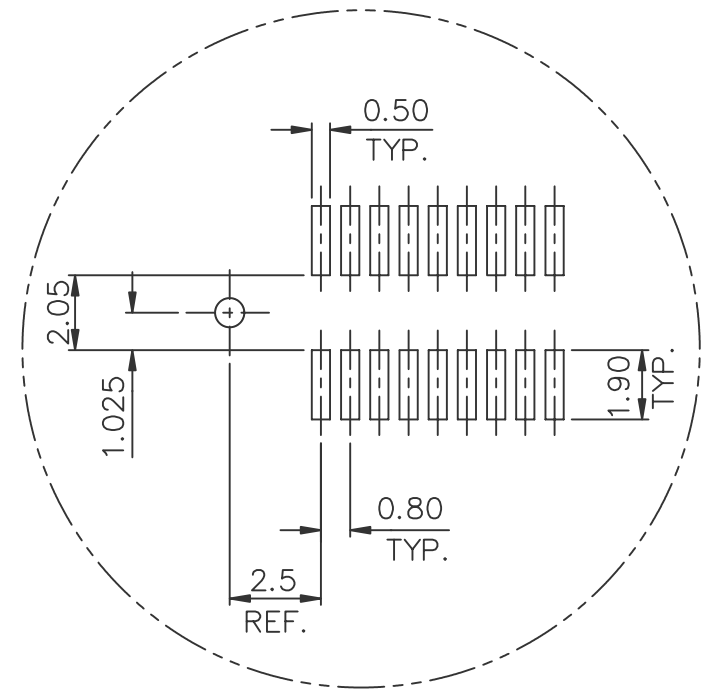
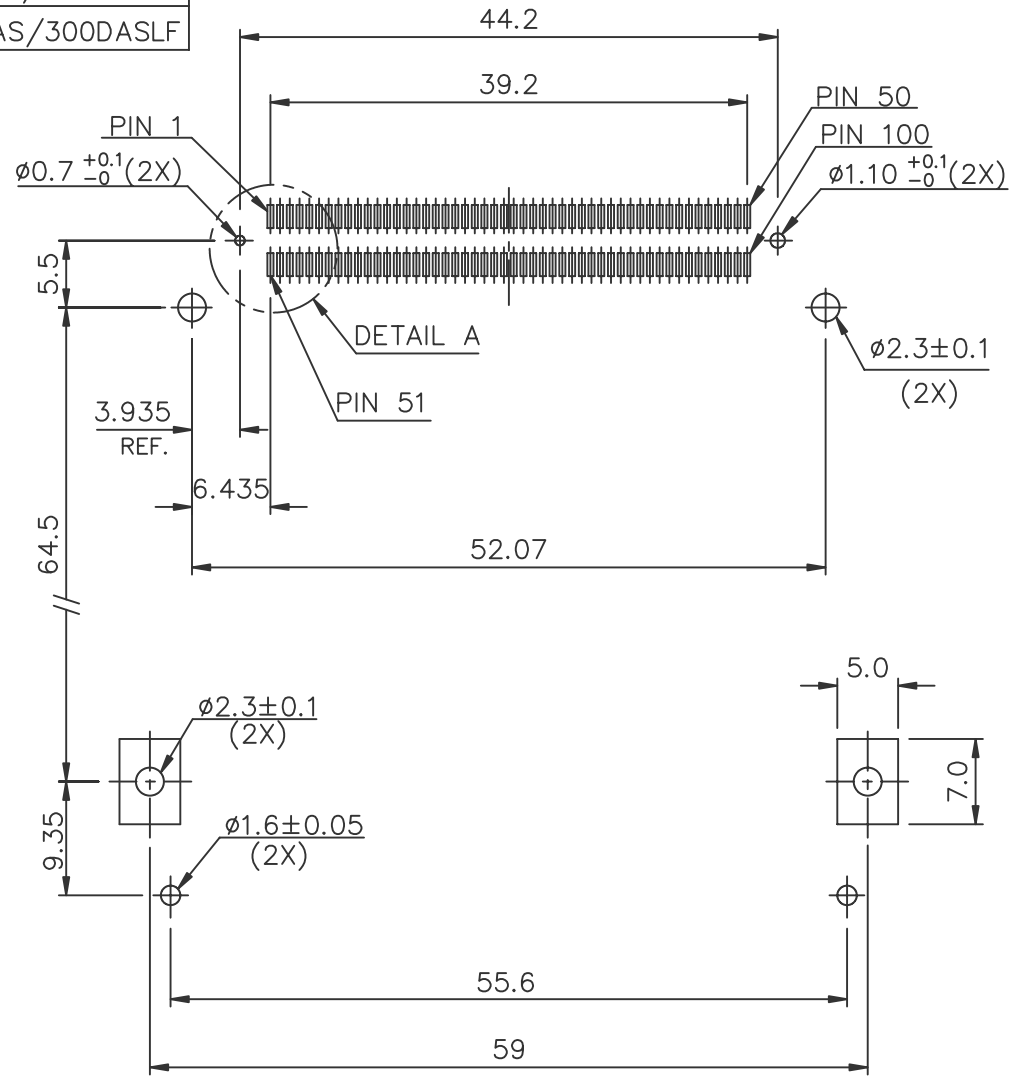
mat'l code				tolerance unless otherwise specified		CUSTOMER COPY		FCI		www.fciconnect.com	
rev.	ecn no.	dr	date	linear	± 0.30	projection	title	CARDBUS EJECT HEADER FORCE-SAVING, TYPE 1/2/3			
A	T90248	WL	07/06/99	angles	± 2'	product family : PCMCIA	code	TWN			
B	T90287	WL	08/03/99			size	dwg no.	sheet			
C	T90359	WL	10/14/99			scale	52366	1 OF 3			
D	T00105	WL	04/11/00	dr	WENDY CHEN	06/25/99					
E	T10151	WL	05/28/01	enr	STELAR CHU	06/25/99					
F	N05-0037	WB	02/16/05	chr	JOSEPH HSIA	06/25/99					
				appd	JENN TSAO	06/25/99					
sheet	revision	F	F	F							
index	sheet	1	2	3							

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PRODUCT NO.
52366-100DAS/100DASLF
52366-300DAS/300DASLF



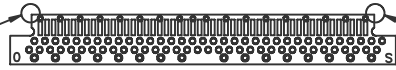
DETAIL A

4 CARD INSERTION DIRECTION

mat'l code		tolerance unless otherwise specified		CUSTOMER COPY	<a href="http://www.fciconnect.com">www.fciconnect.com</a>	
rev.	ecn no.	dr	date	linear	$\pm 0.10$	projection
F				angles	$\pm 2^\circ$	title CARDBUS EJECT HEADER SMT, TYPE 1/2/3
				dr	WENDY CHEN 06/25/99	unit mm/inch
				enrg	STELAR CHU 06/25/99	product family : PCMCIA
				chr	JOSEPH HSIA 06/25/99	size dwg no.
				appd	JENN TSAO 06/25/99	scale 2:1
sheet	revision					A3
index	sheet					52366
						code TWN sheet 3 of 3

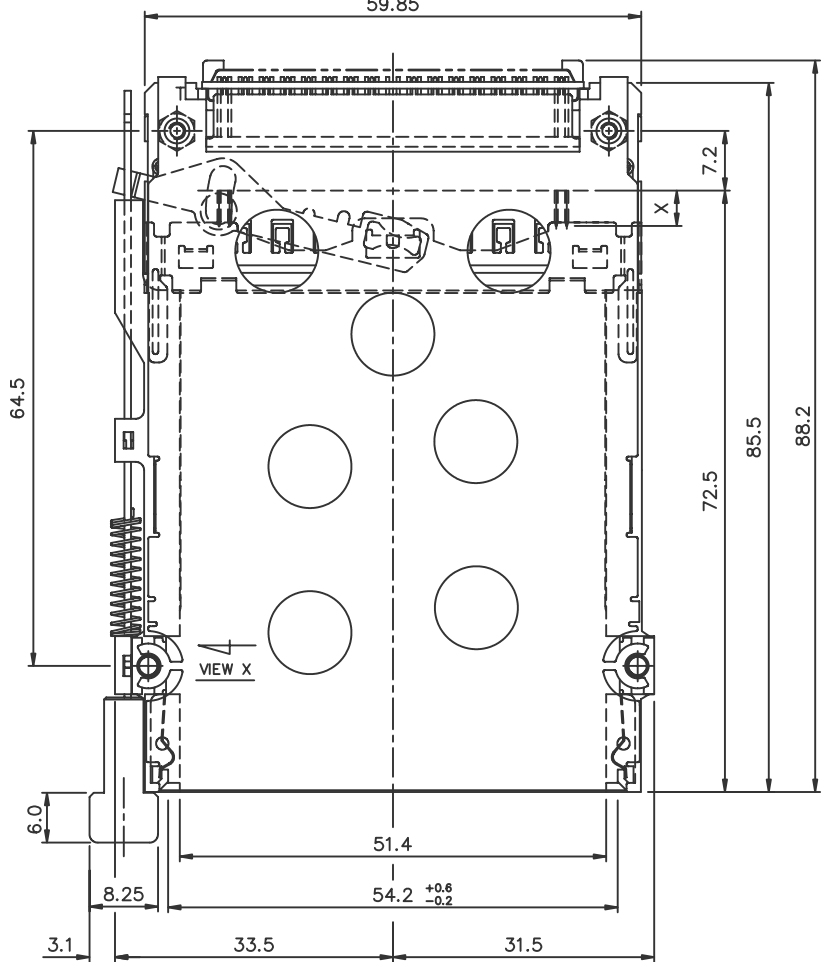
PRODUCT NO.  
52366-300DAS/300DASLF

SEE NOTE 8.1

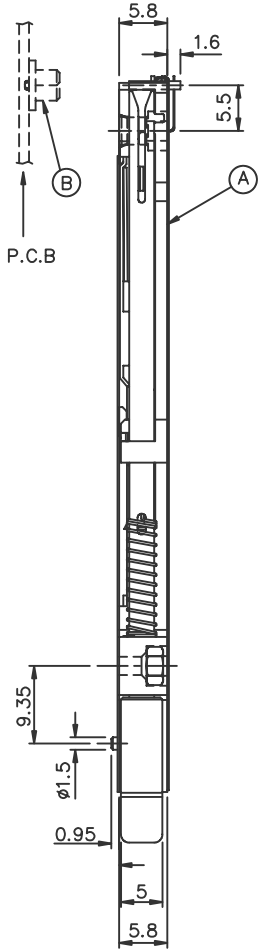


59.85

PCB TOP VIEW



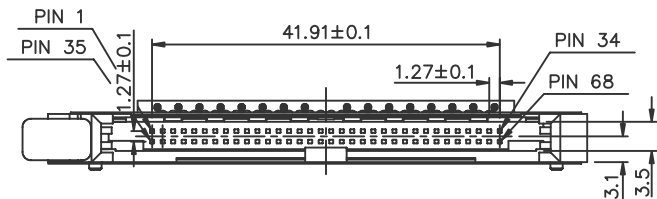
VIEW X



P.C.B



VIEW X  
(SEE NOTE 8.2)



NOTES:

- 1 8.0mm MIN CARD EJECT.
- 2 EJECT TRAVEL: 9.50mm
- 3 MATERIAL:  
EJECT HEADER ASS'Y  
PLASTIC HOUSING: LCP UL94V-0 BLACK  
PIN: COPPER ALLOY  
PCB: FR4  
PLASTIC GUIDE: POLYPHTHARAMID UL94V-0 COLOR : BLACK.  
PLATE: STAINLESS  
EMI CONTACT: PHOSPHOR BRONZE

4 FINISH

- PIN :  
UNDER PLATING: 0.5um MIN. Ni  
CONTACT AREA: 0.1um MIN. GOLD OVER  
0.5um MIN. Pd-Ni

- SOLDER TAIL(TIN LEAD OPTION): 2.5um MIN. Sn-Pb  
SOLDER TAIL(LEAD FREE OPTION): 2.5um MIN. PURE TIN

- GROUND SHIELD :  
UNDER PLATING: 0.75um MIN. Ni  
CONTACT SURFACE: 0.2 um GOLD.

5 PUSH ROD LOCATION AND P.C.B. ARE AS APPEARS INSTALLED

6 DIM "X"

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68

7 DO NOT TOUCH AND KEEP CLEAN THE SURFACES OF PCB OF HEADER ASS'Y.

8 SPECIAL FEATURES:

- 8.1 NO CHAMFER OF VTB
- 8.2 NO "S"-SLOT

9 IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.

10 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBED IN GS-22-008

11 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION

ORDERING INFORMATION

NAME	PART NO.	Q'TY
Ⓐ EJECT HEADER ASS'Y	52366-300DAS/300DASLF	1
Ⓑ MATING RECEPTACLE	73277-101002/101002LF	1

mat'l code	tolerance unless otherwise specified	CUSTOMER COPY	 www.fciconnect.com
rev. ecn no. dr date	linear ± 0.30	projection	
F	angles ± 2°	unit	
	dr WENDY CHEN 06/25/99	mm/inch	
	enrg STELAR CHU 06/25/99	scale	product family : PCMCIA
	chr JOSEPH HSIA 06/25/99	1.5:1	code
	appd JENN TSAO 06/25/99		size dwg no.
sheet revision		A3	52366
index sheet			code
			TWN
			sheet
			2 of